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[Embedded - System On Chip \(SoC\): The Heart of Modern Embedded Systems](#)

[Embedded - System On Chip \(SoC\)](#) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are [Embedded - System On Chip \(SoC\)](#)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

Details

Product Status	Discontinued at Digi-Key
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	256KB
Peripherals	DMA, POR, WDT
Connectivity	EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	1.5GHz
Primary Attributes	FPGA - 660K Logic Elements
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FCBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/10as066n2f40i1sg



Intel® Arria® 10 Device Overview

The Intel® Arria® 10 device family consists of high-performance and power-efficient 20 nm mid-range FPGAs and SoCs.

Intel Arria 10 device family delivers:

- Higher performance than the previous generation of mid-range and high-end FPGAs.
- Power efficiency attained through a comprehensive set of power-saving technologies.

The Intel Arria 10 devices are ideal for high performance, power-sensitive, midrange applications in diverse markets.

Table 1. Sample Markets and Ideal Applications for Intel Arria 10 Devices

Market	Applications
Wireless	<ul style="list-style-type: none"> • Channel and switch cards in remote radio heads • Mobile backhaul
Wireline	<ul style="list-style-type: none"> • 40G/100G muxponders and transponders • 100G line cards • Bridging • Aggregation
Broadcast	<ul style="list-style-type: none"> • Studio switches • Servers and transport • Videoconferencing • Professional audio and video
Computing and Storage	<ul style="list-style-type: none"> • Flash cache • Cloud computing servers • Server acceleration
Medical	<ul style="list-style-type: none"> • Diagnostic scanners • Diagnostic imaging
Military	<ul style="list-style-type: none"> • Missile guidance and control • Radar • Electronic warfare • Secure communications

Related Information

Intel Arria 10 Device Handbook: Known Issues

Lists the planned updates to the *Intel Arria 10 Device Handbook* chapters.



Key Advantages of Intel Arria 10 Devices

Table 2. Key Advantages of the Intel Arria 10 Device Family

Advantage	Supporting Feature
Enhanced core architecture	<ul style="list-style-type: none">Built on TSMC's 20 nm process technology60% higher performance than the previous generation of mid-range FPGAs15% higher performance than the fastest previous-generation FPGA
High-bandwidth integrated transceivers	<ul style="list-style-type: none">Short-reach rates up to 25.8 Gigabits per second (Gbps)Backplane capability up to 12.5 GbpsIntegrated 10GBASE-KR and 40GBASE-KR4 Forward Error Correction (FEC)
Improved logic integration and hard IP blocks	<ul style="list-style-type: none">8-input adaptive logic module (ALM)Up to 65.6 megabits (Mb) of embedded memoryVariable-precision digital signal processing (DSP) blocksFractional synthesis phase-locked loops (PLLs)Hard PCI Express Gen3 IP blocksHard memory controllers and PHY up to 2,400 Megabits per second (Mbps)
Second generation hard processor system (HPS) with integrated ARM* Cortex*-A9* MPCore* processor	<ul style="list-style-type: none">Tight integration of a dual-core ARM Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Intel Arria 10 system-on-a-chip (SoC)Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric
Advanced power savings	<ul style="list-style-type: none">Comprehensive set of advanced power saving featuresPower-optimized MultiTrack routing and core architectureUp to 40% lower power compared to previous generation of mid-range FPGAsUp to 60% lower power compared to previous generation of high-end FPGAs

Summary of Intel Arria 10 Features

Table 3. Summary of Features for Intel Arria 10 Devices

Feature	Description
Technology	<ul style="list-style-type: none">TSMC's 20-nm SoC process technologyAllows operation at a lower V_{CC} level of 0.82 V instead of the 0.9 V standard V_{CC} core voltage
Packaging	<ul style="list-style-type: none">1.0 mm ball-pitch FINELINE BGA packaging0.8 mm ball-pitch Ultra FINELINE BGA packagingMultiple devices with identical package footprints for seamless migration between different FPGA densitiesDevices with compatible package footprints allow migration to next generation high-end Stratix® 10 devicesRoHS, leaded⁽¹⁾, and lead-free (Pb-free) options
High-performance FPGA fabric	<ul style="list-style-type: none">Enhanced 8-input ALM with four registersImproved multi-track routing architecture to reduce congestion and improve compilation timeHierarchical core clocking architectureFine-grained partial reconfiguration
Internal memory blocks	<ul style="list-style-type: none">M20K—20-Kb memory blocks with hard error correction code (ECC)Memory logic array block (MLAB)—640-bit memory
continued...	

(1) Contact Intel for availability.



Feature	Description	
Embedded Hard IP blocks	Variable-precision DSP	<ul style="list-style-type: none">Native support for signal processing precision levels from 18 x 19 to 54 x 54Native support for 27 x 27 multiplier mode64-bit accumulator and cascade for systolic finite impulse responses (FIRs)Internal coefficient memory banksPreadder/subtractor for improved efficiencyAdditional pipeline register to increase performance and reduce powerSupports floating point arithmetic:<ul style="list-style-type: none">Perform multiplication, addition, subtraction, multiply-add, multiply-subtract, and complex multiplication.Supports multiplication with accumulation capability, cascade summation, and cascade subtraction capability.Dynamic accumulator reset control.Support direct vector dot and complex multiplication chaining multiply floating point DSP blocks.
	Memory controller	DDR4, DDR3, and DDR3L
	PCI Express*	PCI Express (PCIe*) Gen3 (x1, x2, x4, or x8), Gen2 (x1, x2, x4, or x8) and Gen1 (x1, x2, x4, or x8) hard IP with complete protocol stack, endpoint, and root port
	Transceiver I/O	<ul style="list-style-type: none">10GBASE-KR/40GBASE-KR4 Forward Error Correction (FEC)PCS hard IPs that support:<ul style="list-style-type: none">10-Gbps Ethernet (10GbE)PCIe PIPE interfaceInterlakenGbps Ethernet (GbE)Common Public Radio Interface (CPRI) with deterministic latency supportGigabit-capable passive optical network (GPON) with fast lock-time support13.5G JESD204b8B/10B, 64B/66B, 64B/67B encoders and decodersCustom mode support for proprietary protocols
Core clock networks	<ul style="list-style-type: none">Up to 800 MHz fabric clocking, depending on the application:<ul style="list-style-type: none">667 MHz external memory interface clocking with 2,400 Mbps DDR4 interface800 MHz LVDS interface clocking with 1,600 Mbps LVDS interfaceGlobal, regional, and peripheral clock networksClock networks that are not used can be gated to reduce dynamic power	
Phase-locked loops (PLLs)	<ul style="list-style-type: none">High-resolution fractional synthesis PLLs:<ul style="list-style-type: none">Precision clock synthesis, clock delay compensation, and zero delay buffering (ZDB)Support integer mode and fractional modeFractional mode support with third-order delta-sigma modulationInteger PLLs:<ul style="list-style-type: none">Adjacent to general purpose I/OsSupport external memory and LVDS interfaces	
FPGA General-purpose I/Os (GPIOs)	<ul style="list-style-type: none">1.6 Gbps LVDS—every pair can be configured as receiver or transmitterOn-chip termination (OCT)1.2 V to 3.0 V single-ended LVTTTL/LVCMOS interfacing	
External Memory Interface	<ul style="list-style-type: none">Hard memory controller—DDR4, DDR3, and DDR3L support<ul style="list-style-type: none">DDR4—speeds up to 1,200 MHz/2,400 MbpsDDR3—speeds up to 1,067 MHz/2,133 MbpsSoft memory controller—provides support for RLDRAM 3⁽²⁾, QDR IV⁽²⁾, and QDR II+	
continued...		



Maximum Resources

Table 5. Maximum Resource Counts for Intel Arria 10 GX Devices (GX 160, GX 220, GX 270, GX 320, and GX 480)

Resource		Product Line				
		GX 160	GX 220	GX 270	GX 320	GX 480
Logic Elements (LE) (K)		160	220	270	320	480
ALM		61,510	80,330	101,620	119,900	183,590
Register		246,040	321,320	406,480	479,600	734,360
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620
	MLAB	1,050	1,690	2,452	2,727	4,164
Variable-precision DSP Block		156	192	830	985	1,368
18 x 19 Multiplier		312	384	1,660	1,970	2,736
PLL	Fractional Synthesis	6	6	8	8	12
	I/O	6	6	8	8	12
17.4 Gbps Transceiver		12	12	24	24	36
GPIO ⁽³⁾		288	288	384	384	492
LVDS Pair ⁽⁴⁾		120	120	168	168	222
PCIe Hard IP Block		1	1	2	2	2
Hard Memory Controller		6	6	8	8	12

⁽³⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁴⁾ Each LVDS I/O pair can be used as differential input or output.



Table 6. Maximum Resource Counts for Intel Arria 10 GX Devices (GX 570, GX 660, GX 900, and GX 1150)

Resource		Product Line			
		GX 570	GX 660	GX 900	GX 1150
Logic Elements (LE) (K)		570	660	900	1,150
ALM		217,080	251,680	339,620	427,200
Register		868,320	1,006,720	1,358,480	1,708,800
Memory (Kb)	M20K	36,000	42,620	48,460	54,260
	MLAB	5,096	5,788	9,386	12,984
Variable-precision DSP Block		1,523	1,687	1,518	1,518
18 x 19 Multiplier		3,046	3,374	3,036	3,036
PLL	Fractional Synthesis	16	16	32	32
	I/O	16	16	16	16
17.4 Gbps Transceiver		48	48	96	96
GPIO ⁽³⁾		696	696	768	768
LVDS Pair ⁽⁴⁾		324	324	384	384
PCIe Hard IP Block		2	2	4	4
Hard Memory Controller		16	16	16	16

Package Plan

Table 7. Package Plan for Intel Arria 10 GX Devices (U19, F27, and F29)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)			F27 (27 mm × 27 mm, 672-pin FBGA)			F29 (29 mm × 29 mm, 780-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
GX 160	48	192	6	48	192	12	48	240	12
GX 220	48	192	6	48	192	12	48	240	12
GX 270	—	—	—	48	192	12	48	312	12
GX 320	—	—	—	48	192	12	48	312	12
GX 480	—	—	—	—	—	—	48	312	12



Related Information

I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

Intel Arria 10 SX

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

Related Information

Intel FPGA Product Selector

Provides the latest information on Intel products.

Available Options

Figure 3. Sample Ordering Code and Available Options for Intel Arria 10 SX Devices



Related Information

Transceiver Performance for Intel Arria 10 GX/SX Devices

Provides more information about the transceiver speed grade.



I/O Vertical Migration for Intel Arria 10 Devices

Figure 4. Migration Capability Across Intel Arria 10 Product Lines

- The arrows indicate the migration paths. The devices included in each vertical migration path are shaded. Devices with fewer resources in the same path have lighter shades.
- To achieve the full I/O migration across product lines in the same migration path, restrict I/Os and transceivers usage to match the product line with the lowest I/O and transceiver counts.
- An LVDS I/O bank in the source device may be mapped to a 3 V I/O bank in the target device. To use memory interface clock frequency higher than 533 MHz, assign external memory interface pins only to banks that are LVDS I/O in both devices.
- There may be nominal 0.15 mm package height difference between some product lines in the same package type.
- Some migration paths are not shown in the Intel Quartus Prime software **Pin Migration View**.

Variant	Product Line	Package										
		U19	F27	F29	F34	F35	KF40	NF40	RF40	NF45	SF45	UF45
Intel® Arria® 10 GX	GX 160	↑	↑	↑								
	GX 220	↓	↓	↓								
	GX 270		↓	↓	↑	↑						
	GX 320		↓	↓	↑	↑						
	GX 480			↓	↑	↑						
	GX 570				↑	↑	↑	↑				
	GX 660				↑	↑	↑	↑	↑	↑	↑	↑
	GX 900				↑			↑	↑	↑	↑	↑
	GX 1150				↑			↑	↑	↑	↑	↑
	GT 900										↑	↑
	GT 1150										↑	↑
Intel Arria 10 SX	SX 160	↑	↑	↑								
	SX 220	↓	↓	↓								
	SX 270		↓	↓	↑	↑						
	SX 320		↓	↓	↑	↑						
	SX 480			↓	↑	↑						
	SX 570				↑	↑	↑	↑				
	SX 660				↑	↑	↑	↑				

Note: To verify the pin migration compatibility, use the **Pin Migration View** window in the Intel Quartus Prime software Pin Planner.

Adaptive Logic Module

Intel Arria 10 devices use a 20 nm ALM as the basic building block of the logic fabric.

The ALM architecture is the same as the previous generation FPGAs, allowing for efficient implementation of logic functions and easy conversion of IP between the device generations.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than the traditional two-register per LUT architecture.

Figure 5. ALM for Intel Arria 10 Devices



The Intel Quartus Prime software optimizes your design according to the ALM logic structure and automatically maps legacy designs into the Intel Arria 10 ALM architecture.

Variable-Precision DSP Block

The Intel Arria 10 variable precision DSP blocks support fixed-point arithmetic and floating-point arithmetic.

Features for fixed-point arithmetic:

- High-performance, power-optimized, and fully registered multiplication operations
- 18-bit and 27-bit word lengths
- Two 18 x 19 multipliers or one 27 x 27 multiplier per DSP block
- Built-in addition, subtraction, and 64-bit double accumulation register to combine multiplication results
- Cascading 19-bit or 27-bit when pre-adder is disabled and cascading 18-bit when pre-adder is used to form the tap-delay line for filtering applications
- Cascading 64-bit output bus to propagate output results from one block to the next block without external logic support
- Hard pre-adder supported in 19-bit and 27-bit modes for symmetric filters
- Internal coefficient register bank in both 18-bit and 27-bit modes for filter implementation
- 18-bit and 27-bit systolic finite impulse response (FIR) filters with distributed output adder
- Biased rounding support



Variant	Product Line	Variable-precision DSP Block	Independent Input and Output Multiplications Operator		18 x 19 Multiplier Adder Sum Mode	18 x 18 Multiplier Adder Summed with 36 bit Input
			18 x 19 Multiplier	27 x 27 Multiplier		
	SX 320	984	1,968	984	984	984
	SX 480	1,368	2,736	1,368	1,368	1,368
	SX 570	1,523	3,046	1,523	1,523	1,523
	SX 660	1,687	3,374	1,687	1,687	1,687

Table 17. Resources for Floating-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line	Variable-precision DSP Block	Single Precision Floating-Point Multiplication Mode	Single-Precision Floating-Point Adder Mode	Single-Precision Floating-Point Multiply Accumulate Mode	Peak Giga Floating-Point Operations per Second (GFLOPs)
Intel Arria 10 GX	GX 160	156	156	156	156	140
	GX 220	192	192	192	192	173
	GX 270	830	830	830	830	747
	GX 320	984	984	984	984	886
	GX 480	1,369	1,368	1,368	1,368	1,231
	GX 570	1,523	1,523	1,523	1,523	1,371
	GX 660	1,687	1,687	1,687	1,687	1,518
	GX 900	1,518	1,518	1,518	1,518	1,366
	GX 1150	1,518	1,518	1,518	1,518	1,366
Intel Arria 10 GT	GT 900	1,518	1,518	1,518	1,518	1,366
	GT 1150	1,518	1,518	1,518	1,518	1,366
Intel Arria 10 SX	SX 160	156	156	156	156	140
	SX 220	192	192	192	192	173
	SX 270	830	830	830	830	747
	SX 320	984	984	984	984	886
	SX 480	1,369	1,368	1,368	1,368	1,231
	SX 570	1,523	1,523	1,523	1,523	1,371
	SX 660	1,687	1,687	1,687	1,687	1,518

Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.



Types of Embedded Memory

The Intel Arria 10 devices contain two types of memory blocks:

- 20 Kb M20K blocks—blocks of dedicated memory resources. The M20K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide and shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Intel Arria 10 devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

Embedded Memory Capacity in Intel Arria 10 Devices

Table 18. Embedded Memory Capacity and Distribution in Intel Arria 10 Devices

Variant	Product Line	M20K		MLAB		Total RAM Bit (Kb)
		Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	
Intel Arria 10 GX	GX 160	440	8,800	1,680	1,050	9,850
	GX 220	587	11,740	2,703	1,690	13,430
	GX 270	750	15,000	3,922	2,452	17,452
	GX 320	891	17,820	4,363	2,727	20,547
	GX 480	1,431	28,620	6,662	4,164	32,784
	GX 570	1,800	36,000	8,153	5,096	41,096
	GX 660	2,131	42,620	9,260	5,788	48,408
	GX 900	2,423	48,460	15,017	9,386	57,846
	GX 1150	2,713	54,260	20,774	12,984	67,244
Intel Arria 10 GT	GT 900	2,423	48,460	15,017	9,386	57,846
	GT 1150	2,713	54,260	20,774	12,984	67,244
Intel Arria 10 SX	SX 160	440	8,800	1,680	1,050	9,850
	SX 220	587	11,740	2,703	1,690	13,430
	SX 270	750	15,000	3,922	2,452	17,452
	SX 320	891	17,820	4,363	2,727	20,547
	SX 480	1,431	28,620	6,662	4,164	32,784
	SX 570	1,800	36,000	8,153	5,096	41,096
	SX 660	2,131	42,620	9,260	5,788	48,408

Embedded Memory Configurations for Single-port Mode

Table 19. Single-port Embedded Memory Configurations for Intel Arria 10 Devices

This table lists the maximum configurations supported for single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width
MLAB	32	x16, x18, or x20
	64 ⁽¹⁰⁾	x8, x9, x10
M20K	512	x40, x32
	1K	x20, x16
	2K	x10, x8
	4K	x5, x4
	8K	x2
	16K	x1

Clock Networks and PLL Clock Sources

The clock network architecture is based on Intel's global, regional, and peripheral clock structure. This clock structure is supported by dedicated clock input pins, fractional clock synthesis PLLs, and integer I/O PLLs.

Clock Networks

The Intel Arria 10 core clock networks are capable of up to 800 MHz fabric operation across the full industrial temperature range. For the external memory interface, the clock network supports the hard memory controller with speeds up to 2,400 Mbps in a quarter-rate transfer.

To reduce power consumption, the Intel Quartus Prime software identifies all unused sections of the clock network and powers them down.

Fractional Synthesis and I/O PLLs

Intel Arria 10 devices contain up to 32 fractional synthesis PLLs and up to 16 I/O PLLs that are available for both specific and general purpose uses in the core:

- Fractional synthesis PLLs—located in the column adjacent to the transceiver blocks
- I/O PLLs—located in each bank of the 48 I/Os

Fractional Synthesis PLLs

You can use the fractional synthesis PLLs to:

- Reduce the number of oscillators that are required on your board
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

⁽¹⁰⁾ Supported through software emulation and consumes additional MLAB blocks.



The fractional synthesis PLLs support the following features:

- Reference clock frequency synthesis for transceiver CMU and Advanced Transmit (ATX) PLLs
- Clock network delay compensation
- Zero-delay buffering
- Direct transmit clocking for transceivers
- Independently configurable into two modes:
 - Conventional integer mode equivalent to the general purpose PLL
 - Enhanced fractional mode with third order delta-sigma modulation
- PLL cascading

I/O PLLs

The integer mode I/O PLLs are located in each bank of 48 I/Os. You can use the I/O PLLs to simplify the design of external memory and high-speed LVDS interfaces.

In each I/O bank, the I/O PLLs are adjacent to the hard memory controllers and LVDS SERDES. Because these PLLs are tightly coupled with the I/Os that need to use them, it makes it easier to close timing.

You can use the I/O PLLs for general purpose applications in the core such as clock network delay compensation and zero-delay buffering.

Intel Arria 10 devices support PLL-to-PLL cascading.

FPGA General Purpose I/O

Intel Arria 10 devices offer highly configurable GPIOs. Each I/O bank contains 48 general purpose I/Os and a high-efficiency hard memory controller.

The following list describes the features of the GPIOs:

- Consist of 3 V I/Os for high-voltage application and LVDS I/Os for differential signaling
 - Up to two 3 V I/O banks, available in some devices, that support up to 3 V I/O standards
 - LVDS I/O banks that support up to 1.8 V I/O standards
- Support a wide range of single-ended and differential I/O interfaces
- LVDS speeds up to 1.6 Gbps
- Each LVDS pair of pins has differential input and output buffers, allowing you to configure the LVDS direction for each pair.
- Programmable bus hold and weak pull-up
- Programmable differential output voltage (V_{OD}) and programmable pre-emphasis



- Series (R_S) and parallel (R_T) on-chip termination (OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture

External Memory Interface

Intel Arria 10 devices offer massive external memory bandwidth, with up to seven 32-bit DDR4 memory interfaces running at up to 2,400 Mbps. This bandwidth provides additional ease of design, lower power, and resource efficiencies of hardened high-performance memory controllers.

The memory interface within Intel Arria 10 FPGAs and SoCs delivers the highest performance and ease of use. You can configure up to a maximum width of 144 bits when using the hard or soft memory controllers. If required, you can bypass the hard memory controller and use a soft controller implemented in the user logic.

Each I/O contains a hardened DDR read/write path (PHY) capable of performing key memory interface functionality such as read/write leveling, FIFO buffering to lower latency and improve margin, timing calibration, and on-chip termination.

The timing calibration is aided by the inclusion of hard microcontrollers based on Intel's Nios® II technology, specifically tailored to control the calibration of multiple memory interfaces. This calibration allows the Intel Arria 10 device to compensate for any changes in process, voltage, or temperature either within the Intel Arria 10 device itself, or within the external memory device. The advanced calibration algorithms ensure maximum bandwidth and robust timing margin across all operating conditions.

In addition to parallel memory interfaces, Intel Arria 10 devices support serial memory technologies such as the Hybrid Memory Cube (HMC). The HMC is supported by the Intel Arria 10 high-speed serial transceivers which connect up to four HMC links, with each link running at data rates up to 15 Gbps.

Related Information

[External Memory Interface Spec Estimator](#)

Provides a parametric tool that allows you to find and compare the performance of the supported external memory interfaces in IntelFPGAs.

Memory Standards Supported by Intel Arria 10 Devices

The I/Os are designed to provide high performance support for existing and emerging external memory standards.

**Table 20. Memory Standards Supported by the Hard Memory Controller**

This table lists the overall capability of the hard memory controller. For specific details, refer to the External Memory Interface Spec Estimator and Intel Arria 10 Device Datasheet.

Memory Standard	Rate Support	Ping Pong PHY Support	Maximum Frequency (MHz)
DDR4 SDRAM	Quarter rate	Yes	1,067
		—	1,200
DDR3 SDRAM	Half rate	Yes	533
		—	667
	Quarter rate	Yes	1,067
		—	1,067
DDR3L SDRAM	Half rate	Yes	533
		—	667
	Quarter rate	Yes	933
		—	933
LPDDR3 SDRAM	Half rate	—	533
	Quarter rate	—	800

Table 21. Memory Standards Supported by the Soft Memory Controller

Memory Standard	Rate Support	Maximum Frequency (MHz)
RLDRAM 3 ⁽¹¹⁾	Quarter rate	1,200
QDR IV SRAM ⁽¹¹⁾	Quarter rate	1,067
QDR II SRAM	Full rate	333
	Half rate	633
QDR II+ SRAM	Full rate	333
	Half rate	633
QDR II+ Xtreme SRAM	Full rate	333
	Half rate	633

Table 22. Memory Standards Supported by the HPS Hard Memory Controller

The hard processor system (HPS) is available in Intel Arria 10 SoC devices only.

Memory Standard	Rate Support	Maximum Frequency (MHz)
DDR4 SDRAM	Half rate	1,200
DDR3 SDRAM	Half rate	1,067
DDR3L SDRAM	Half rate	933

⁽¹¹⁾ Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



Related Information

[Intel Arria 10 Device Datasheet](#)

Lists the memory interface performance according to memory interface standards, rank or chip select configurations, and Intel Arria 10 device speed grades.

PCIe Gen1, Gen2, and Gen3 Hard IP

Intel Arria 10 devices contain PCIe hard IP that is designed for performance and ease-of-use:

- Includes all layers of the PCIe stack—transaction, data link and physical layers.
- Supports PCIe Gen3, Gen2, and Gen1 Endpoint and Root Port in x1, x2, x4, or x8 lane configuration.
- Operates independently from the core logic—optional configuration via protocol (CvP) allows the PCIe link to power up and complete link training in less than 100 ms while the Intel Arria 10 device completes loading the programming file for the rest of the FPGA.
- Provides added functionality that makes it easier to support emerging features such as Single Root I/O Virtualization (SR-IOV) and optional protocol extensions.
- Provides improved end-to-end datapath protection using ECC.
- Supports FPGA configuration via protocol (CvP) using PCIe at Gen3, Gen2, or Gen1 speed.

Related Information

[PCS Features](#) on page 30

Enhanced PCS Hard IP for Interlaken and 10 Gbps Ethernet

Interlaken Support

The Intel Arria 10 enhanced PCS hard IP provides integrated Interlaken PCS supporting rates up to 25.8 Gbps per lane.

The Interlaken PCS is based on the proven functionality of the PCS developed for Intel's previous generation FPGAs, which demonstrated interoperability with Interlaken ASSP vendors and third-party IP suppliers. The Interlaken PCS is present in every transceiver channel in Intel Arria 10 devices.

Related Information

[PCS Features](#) on page 30

10 Gbps Ethernet Support

The Intel Arria 10 enhanced PCS hard IP supports 10GBASE-R PCS compliant with IEEE 802.3 10 Gbps Ethernet (10GbE). The integrated hard IP support for 10GbE and the 10 Gbps transceivers save external PHY cost, board space, and system power.



Figure 7. Device Chip Overview for Intel Arria 10 GX and GT Devices

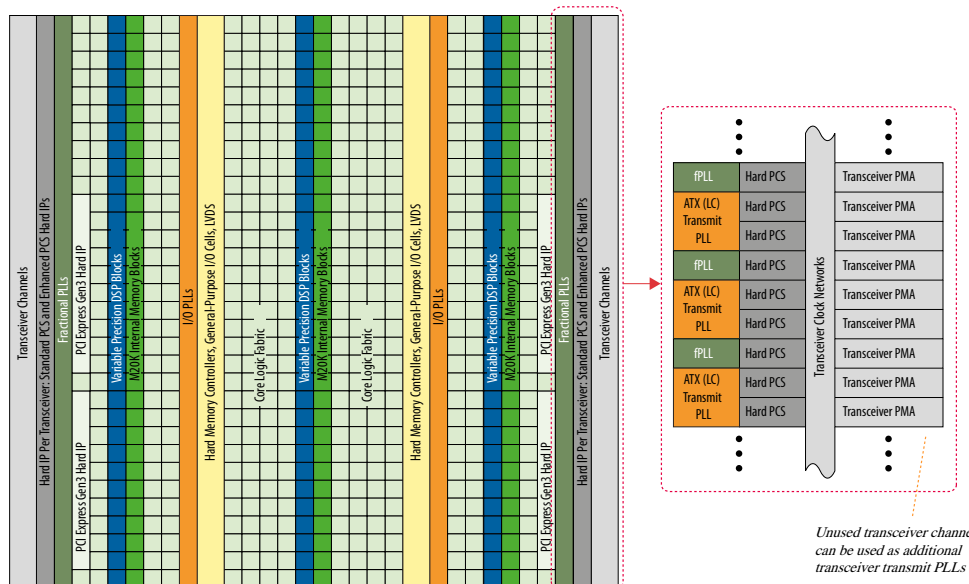


Figure 8. Device Chip Overview for Intel Arria 10 SX Devices



PMA Features

Intel Arria 10 transceivers provide exceptional signal integrity at data rates up to 25.8 Gbps. Clocking options include ultra-low jitter ATX PLLs (LC tank based), clock multiplier unit (CMU) PLLs, and fractional PLLs.



Protocol	Data Rate (Gbps)	Transceiver IP	PCS Support
CPRI 6.0 (64B/66B)	0.6144 to 10.1376	Native PHY	Enhanced PCS
CPRI 4.2 (8B/10B)	0.6144 to 9.8304	Native PHY	Standard PCS
OBSAI RP3 v4.2	0.6144 to 6.144	Native PHY	Standard PCS
SD-SDI/HD-SDI/3G-SDI	0.143 ⁽¹²⁾ to 2.97	Native PHY	Standard PCS

Related Information

[Intel Arria 10 Transceiver PHY User Guide](#)

Provides more information about the supported transceiver protocols and PHY IP, the PMA architecture, and the standard, enhanced, and PCIe Gen3 PCS architecture.

SoC with Hard Processor System

Each SoC device combines an FPGA fabric and a hard processor system (HPS) in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

⁽¹²⁾ The 0.143 Gbps data rate is supported using oversampling of user logic that you must implement in the FPGA fabric.



FPGA Configuration and HPS Booting

The FPGA fabric and HPS in the SoC FPGA must be powered at the same time. You can reduce the clock frequencies or gate the clocks to reduce dynamic power.

Once powered, the FPGA fabric and HPS can be configured independently thus providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or partially reconfigure the FPGA fabric at any time under software control. The HPS can also configure other FPGAs on the board through the FPGA configuration controller.
- Configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer system integration tool in the Intel Quartus Prime software.

For software development, the ARM-based SoC FPGA devices inherit the rich software development ecosystem available for the ARM Cortex-A9 MPCore processor. The software development process for Intel SoC FPGAs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux*, VxWorks*, and other operating systems are available for the SoC FPGAs. For more information on the operating systems support availability, contact the Intel FPGA sales team.

You can begin device-specific firmware and software development on the Intel SoC FPGA Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

Dynamic and Partial Reconfiguration

The Intel Arria 10 devices support dynamic and partial reconfiguration. You can use dynamic and partial reconfiguration simultaneously to enable seamless reconfiguration of both the device core and transceivers.

Dynamic Reconfiguration

You can reconfigure the PMA and PCS blocks while the device continues to operate. This feature allows you to change the data rates, protocol, and analog settings of a channel in a transceiver bank without affecting on-going data transfer in other transceiver banks. This feature is ideal for applications that require dynamic multiprotocol or multirate support.

Partial Reconfiguration

Using partial reconfiguration, you can reconfigure some parts of the device while keeping the device in operation.



Instead of placing all device functions in the FPGA fabric, you can store some functions that do not run simultaneously in external memory and load them only when required. This capability increases the effective logic density of the device, and lowers cost and power consumption.

In the Intel solution, you do not have to worry about intricate device architecture to perform a partial reconfiguration. The partial reconfiguration capability is built into the Intel Quartus Prime design software, making such time-intensive task simple.

Intel Arria 10 devices support partial reconfiguration in the following configuration options:

- Using an internal host:
 - All supported configuration modes where the FPGA has access to external memory devices such as serial and parallel flash memory.
 - Configuration via Protocol [CvP (PCIe)]
- Using an external host—passive serial (PS), fast passive parallel (FPP) x8, FPP x16, and FPP x32 I/O interface.

Enhanced Configuration and Configuration via Protocol

Table 25. Configuration Schemes and Features of Intel Arria 10 Devices

Intel Arria 10 devices support 1.8 V programming voltage and several configuration schemes.

Scheme	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps) ⁽¹³⁾	Decompression	Design Security ⁽¹⁴⁾	Partial Reconfiguration ⁽¹⁵⁾	Remote System Update
JTAG	1 bit	33	33	—	—	Yes ⁽¹⁶⁾	—
Active Serial (AS) through the EPCQ-L configuration device	1 bit, 4 bits	100	400	Yes	Yes	Yes ⁽¹⁶⁾	Yes
Passive serial (PS) through CPLD or external microcontroller	1 bit	100	100	Yes	Yes	Yes ⁽¹⁶⁾	Parallel Flash Loader (PFL) IP core

continued...

⁽¹³⁾ Enabling either compression or design security features affects the maximum data rate. Refer to the Intel Arria 10 Device Datasheet for more information.

⁽¹⁴⁾ Encryption and compression cannot be used simultaneously.

⁽¹⁵⁾ Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Intel for support.

⁽¹⁶⁾ Partial configuration can be performed only when it is configured as internal host.



Date	Version	Changes
August 2014	2014.08.18	<ul style="list-style-type: none"> Updated Memory (Kb) M20K maximum resources for Arria 10 GX 660 devices from 42,660 to 42,620. Added GPIO columns consisting of LVDS I/O Bank and 3V I/O Bank in the Package Plan table. Added how to use memory interface clock frequency higher than 533 MHz in the I/O vertical migration. Added information to clarify that RLDRAM3 support uses hard PHY with soft memory controller. Added variable precision DSP blocks support for floating-point arithmetic.
June 2014	2014.06.19	Updated number of dedicated I/Os in the HPS block to 17.
February 2014	2014.02.21	Updated transceiver speed grade options for GT devices in Figure 2.
February 2014	2014.02.06	Updated data rate for Arria 10 GT devices from 28.1 Gbps to 28.3 Gbps.
December 2013	2013.12.10	<ul style="list-style-type: none"> Updated the HPS memory standards support from LPDDR2 to LPDDR3. Updated HPS block diagram to include dedicated HPS I/O and FPGA Configuration blocks as well as repositioned SD/SDIO/MMC, DMA, SPI and NAND Flash with ECC blocks .
December 2013	2013.12.02	Initial release.